



HPQ ANNOUNCES NON-BROKER PRIVATE PLACEMENT OF UNITS

NOT FOR DISTRIBUTION TO U.S NEWS WIRES OR DISSEMINATION IN THE U.S

MONTREAL, Canada, May 29th, 2025 — [HPQ Silicon Inc.](#) (“HPQ” or the “Company”) (TSX-V: [HPQ](#), OTCQB: [HPQFF](#), FRA: [O08](#)), a technology company driving innovation in advanced materials and critical process development, is pleased to announce that it intends to proceed with a non-brokered private placement of 2,300,000 Units to \$414,000. The Company intends to use the net proceed to finance its ongoing initiatives and general corporate purposes.

Private placement highlights: Non-Brokered Private placement of 2,300,000 Units at a price of \$0.18 per unit for a gross proceed of \$414,000. The Company reserves the right to increase the size of the Offering to a maximum of 5,283,050 Units, for maximum gross proceeds of \$950,950.

Each Unit is comprised of one (1) common share and one (1) common share purchase warrant of the Company. Each Warrant will entitle the holder thereof to purchase one common share of the capital stock of the Company at an exercise price of \$ 0.25 for a period of 48 months from the date of closing of the placement. Each share issued pursuant to the placement will have a mandatory four (4) month and one (1) day holding period from the date of closing of the placement. The offering will be offered to accredited investors in accordance with applicable securities laws.

This Placement is subject to the approval of the TSX-Venture and any other regulatory authorities. In connection with the placement, the company could pay finder's fee, in the form of cash, shares, warrants and or options.

The company anticipates that insiders may subscribe for units and their participation could exceed 25 per cent of the offering, with the President and CEO, directly or via entities under his controls will subscribe for an amount of \$200,160.

“We decided to proceed with a small financing at this time to provide HPQ with the foundation necessary to capitalize on the larger opportunities we are currently advancing,” said Bernard Tourillon, President and CEO of HPQ Silicon Inc.

About HPQ Silicon

[HPQ Silicon Inc.](#) (TSX-V: [HPQ](#)) is a Quebec-based TSX Venture Exchange Industrial Issuer.

HPQ is a technology company focused on innovation in advanced materials and critical process development. In partnership with world-class technology leaders [PyroGenesis Inc.](#) and [NOVACIUM SAS](#)—of which HPQ is a shareholder—the company is developing the materials and process technologies essential to achieving net-zero goals.

HPQ activities are centred around the following pillars:

- 1) Becoming a green, low-cost (Capex and Opex) manufacturer of Fumed Silica using the **FUMED SILICA REACTOR**, a proprietary technology owned by HPQ Silica Polvere Inc., being developed for HSPI by PyroGenesis.
- 2) Working with R&D partner NOVACIUM SAS, to become a producer of silicon-based anode materials for battery applications.
- 3) Developing Innovative processes to generate and use Hydrogen:
 - a. **METAGENE™**, a low-carbon, chemical-based, on-demand, high-pressure autonomous hydrogen production system, is being developed by NOVACIUM SAS of which HPQ holds



the exclusive North American (Canada, USA, and Mexico) license.

- b. **WASTE TO ENERGY (W2E)**, a new process to transform black aluminum dross into a valuable resource, is being developed by NOVACIUM SAS, of which HPQ holds the exclusive North American (Canada, USA, and Mexico) license. HPQ is also a shareholder in NOVACIUM SAS.
- 4) Becoming a zero-CO₂ low-cost (Capex and Opex) producer of High Purity Silicon (2N+ to 4N) using our **PUREVAP™ “Quartz Reduction Reactors” (QRR)**, a proprietary technology owned by HPQ being developed for HPQ by PyroGenesis.

For more information, please visit [HPQ Silicon web site](#).

Disclaimers:

This press release contains certain forward-looking statements, including, without limitation, statements containing the words "may", "plan", "will", "estimate", "continue", "anticipate", "intend", "expect", "in the process" and other similar expressions which constitute "forward-looking information" within the meaning of applicable securities laws. Forward-looking statements reflect the Company's current expectation and assumptions and are subject to a number of risks and uncertainties that could cause actual results to differ materially from those anticipated. These forward-looking statements involve risks and uncertainties including, but not limited to, our expectations regarding the acceptance of our products by the market, our strategy to develop new products and enhance the capabilities of existing products, our strategy with respect to research and development, the impact of competitive products and pricing, new product development, and uncertainties related to the regulatory approval process. Such statements reflect the current views of the Company with respect to future events and are subject to certain risks and uncertainties and other risks detailed from time-to-time in the Company's ongoing filings with the security's regulatory authorities, which filings can be found at www.sedar.com. Actual results, events, and performance may differ materially. Readers are cautioned not to place undue reliance on these forward-looking statements. The Company undertakes no obligation to publicly update or revise any forward-looking statements either as a result of new information, future events or otherwise, except as required by applicable securities laws.

Neither the TSX Venture Exchange nor its Regulation Services Provider (as that term is defined in the policies of the TSX Venture Exchange) accepts responsibility for the adequacy or accuracy of this release.

This News Release is available on the company's [CEO Verified Discussion Forum](#), a moderated social media platform that enables civilized discussion and Q&A between Management and Shareholders.

Source: HPQ Silicon Inc.

For further information contact:

Bernard J. Tourillon, Chairman, President, and CEO Tel +1 (514) 846-3271

Email: Info@hpqsilicon.com